

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00825	4.44	0.12432
	Doped silicon	Silicon (Si)	7440-21-3	0.17785	95.67	2.67876
Subtotal				0.1861	100.11	2.80308
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03869	10.0	0.58271
	Silver alloy	Silver (Ag)	7440-22-4	0.00774	2.0	0.11654
	Lead alloy	Lead (Pb)	7439-92-1	0.34044	88.0	5.12782
Subtotal				0.38687	100	5.82707
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27939	100.0	4.20829
	Subtotal				0.27939	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00976	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.0065	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00976	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03577	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.45578	99.81	488.8594
Subtotal				32.51757	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34304	100.0	5.167
	Subtotal				0.34304	100
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.30298	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.69267	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46401	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19886	0.3	2.99532
	Polymer	Epoxy resin system		6.62872	10.0	99.844
Subtotal				66.28724	100	998.44
Total				100.00021	100	1506.23545

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